



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EC
1803
26/6

Applicant : Charles F. Drill, et al.
Appl. No : 08/824,633
Filed : March 27, 1997
Title : A Customized Polishing Pad For
Selective Process Performance
During Chemical Mechanical
Polishing

Grp./Art Unit : 3723
Examiner: M. Rachuba

COPY OF PAPERS
ORIGINALLY FILED

Docket No. : PHA 51265B

Assistant Commissioner for Patents
Washington DC 20231

RESPONSE and AMENDMENT

Sir:

This is in response to the Office Action of April, 22, 2002.

IN THE CLAIMS

Please cancel Claims 18-19, which have been withdrawn from consideration, without prejudice or disclaimer.

Please cancel pending Claims 1, 3, 4, 8-10, 12, 16-17, and 20-21 without prejudice or disclaimer.

Please add new Claims 22-35.

1 22. (New) A polishing pad suitable for chemical mechanical polishing of wafers,

2 comprising:

3 a circular base layer and an overlying circular top layer, the overlying circular top

4 layer forming the polishing surface of the polishing pad;

5 wherein the polishing surface of the polishing pad has at least two polishing

6 regions thereon, the at least two polishing regions having distinct polishing

7 characteristics, and wherein the at least two polishing regions are disposed on the

8 polishing pad as concentric annular regions.

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